

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chao-Tung Yang	07/20/2008
Shuo Yuan Hsiao	07/20/2008
Fucheng Wang	07/20/2008
RECEIVING PARTY DATA	
Name:	MStar Semiconductor, Inc.
Street Address:	4F-1, Number 26, Tai-Yuan St.
City:	ChuPei, Hsinchu Hsien
State/Country:	TAIWAN
Postal Code:	302
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12211277
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Total Attachments: 1 source=ExecutedAssignment#page1.tif	

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ASSIGNMENT

For good and valuable consideration, We, **Chao-Tung Yang, Hsiao, Shuo Yuan, and FUCHENG WANG**, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **MStar Semiconductor, Inc.**, having its principal place of business at 4F-1, Number 26, Tai-Yuan St. Chupei, Hsinchu Hsien 302, Taiwan, R.O.C., hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on _____ as US. Application Serial No. _____,

entitled: *Transconductor Having High Linearity and Programmable Gain and Mixer Using the Same*

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: *Chao-Tung Yang* DATE: *July 20, 2008*
Chao-Tung Yang
SIGNATURE: *Hsiao, Shuo Yuan* DATE: *July 20, 2008*
Hsiao, Shuo Yuan
SIGNATURE: *Fucheng Wang* DATE: *July 20, 2008*
FUCHENG WANG